IN THE CLAIMS

Please amend the claims as follows.

1. (currently amended) A discrete package comprising:

a lead frame pad which has a first surface and a second surface, the second surface which is the opposite surface of the first surface;

leads connected to a side of the lead frame pad;

a semiconductor chip attached to the first surface of the lead frame pad;

a ceramic layer having a first and second surface and which is positioned to directly contact the second surface of the lead frame pad; and

a molding material which entirely encapsulates the lead frame pad, the semiconductor chip, and a portion of the ceramic layer, except the leads and the second surface of the ceramic layer.

2. (currently amended) The discrete package of claim 1, wherein the leads are ~~formed to have steps~~ stepped with respect to the lead frame pad.

3. (original) The discrete package of claim 1, further comprising wires which electrically connect the leads to the semiconductor chip.

4. (original) The discrete package of claim 1, wherein the lead frame pad is formed to a thickness of 0.5 mm.

5. (original) The discrete package of claim 1, further comprising an adhesive between the lead frame pad and the semiconductor chip.

6. (currently amended) A discrete package comprising:

a lead frame pad which has a first surface and a second surface, the second surface which is the opposite surface of the first surface;

leads which are connected to a side of the lead frame pad;

a semiconductor chip which is attached to the first surface of the lead frame pad;

a ceramic layer having a first and second surface and which is directly attached ~~with~~ to the second surface of the lead frame pad via an epoxy; and

a molding material which entirely encapsulates the lead frame pad, the semiconductor chip, and a portion of the ceramic layer, except the leads and the second surface of the ceramic layer.

7. (currently amended) The discrete package of claim 6, wherein the leads are ~~formed to have steps~~ stepped with respect to the lead frame pad.

8. (original) The discrete package of claim 6, further comprising wires which electrically connect the leads to the semiconductor chip.

9. (original) The discrete package of claim 6, wherein the lead frame pad is formed to a thickness of 0.5 mm.

10. (original) The discrete package of claim 6, further comprising an adhesive between the lead frame pad and the semiconductor chip.

11. (currently amended) A discrete semiconductor package, comprising:

a lead frame having a first surface and a second surface with a lead connected to the lead frame;

a semiconductor chip attached to the first surface of the lead frame;

a ceramic layer having a first surface and a second surface, wherein the first surface of the ceramic layer is directly attached to the second surface of the lead frame; and

a molding material which encapsulates the lead frame, the semiconductor chip, a portion of the lead, and ~~a portion of the second surface of~~ the ceramic layer except for the second surface.

12. (original) The package of claim 11, wherein the first surface of the ceramic layer does not contain a conductive layer.

13. (original) The package of claim 11, wherein the ceramic layer is attached to the lead frame by using the molding material.

14. (currently amended) A discrete semiconductor package, comprising:

a lead frame having a first surface and a second surface with a lead connected to the lead frame;

a semiconductor chip attached to the first surface of the lead frame;

a ceramic layer having a first surface and a second surface, wherein the first surface of the ceramic layer is directly attached to the second surface of the lead frame via an epoxy; and

a molding material which encapsulates the lead frame, the semiconductor chip, a portion of the lead, and ~~a portion of the second surface of~~ the ceramic layer except for the second surface.

15. (currently amended) An electronic apparatus containing a packaged semiconductor device, the device comprising:

a lead frame having a first surface and a second surface with a lead connected to the lead frame;

a semiconductor chip attached to the first surface of the lead frame;

a ceramic layer having a first surface and a second surface, wherein the first surface of the ceramic does not contain a conductive layer and is attached to the second surface of the lead frame; and

a molding material which encapsulates the lead frame, the semiconductor chip, a portion of the lead, and ~~a portion of the second surface of~~ the ceramic layer except for the second surface.

16. (original) The apparatus of claim 15, wherein the first surface of the ceramic layer is directly attached to the second surface of the lead frame.

17. (original) The apparatus of claim 15, wherein the ceramic layer is attached to the lead frame by using the molding material.

18. (original) The apparatus of claim 15, wherein the ceramic layer is attached to the lead frame via an epoxy located between ceramic layer and the lead frame.

19. (currently amended) A method for making a packaged semiconductor device, comprising:

providing a lead frame having a first surface and a second surface with a lead connected to the lead frame;

providing a semiconductor chip attached to the first surface of the lead frame;

providing a ceramic layer having a first surface and a second surface, wherein the first surface of the ceramic does not contain a conductive layer and is attached to the second surface of the lead frame; and

providing a molding material which encapsulates the lead frame, the semiconductor chip, a portion of the lead, and ~~a portion of the second surface of~~ the ceramic layer except for the second surface.

20. (currently amended) A method for making a packaged semiconductor device, comprising:

providing a lead frame having a first surface and a second surface with a lead connected to the lead frame;

attaching a semiconductor chip to the first surface of the lead frame;

attaching a first surface of a ceramic layer to the second surface of the lead frame, wherein the first surface of the ceramic layer does not contain a conductive layer; and

encapsulating the lead frame, the semiconductor chip, a portion of the lead, and ~~a portion of the second surface of~~ the ceramic layer except for the second surface.

21. (original) The method of claim 20, further comprising directly attaching the first surface of the ceramic layer to the second surface of the lead frame.

22. (original) The method of claim 20, wherein the encapsulation is performed using a molding material.

23. (original) The method of claim 22, further comprising attaching the ceramic layer to the lead frame by using the molding material.

24. (original) The method of claim 20, further comprising attaching the ceramic layer to the lead frame by using an epoxy.

25. (currently amended) A method for making an electronic apparatus, comprising:

providing a packaged semiconductor device by providing a lead frame having a first surface and a second surface with a lead connected to the lead frame, attaching a semiconductor chip to the first surface of the lead frame, attaching a first surface of a ceramic layer to the second surface of the lead frame, wherein the first surface of the ceramic layer does not contain a conductive layer, and encapsulating the lead frame, the semiconductor chip, a portion of the lead, and ~~a portion of the second surface of~~ the ceramic layer except for the second surface;

providing an outer heat sink; and

connecting the packaged semiconductor device to the outer heat sink.